

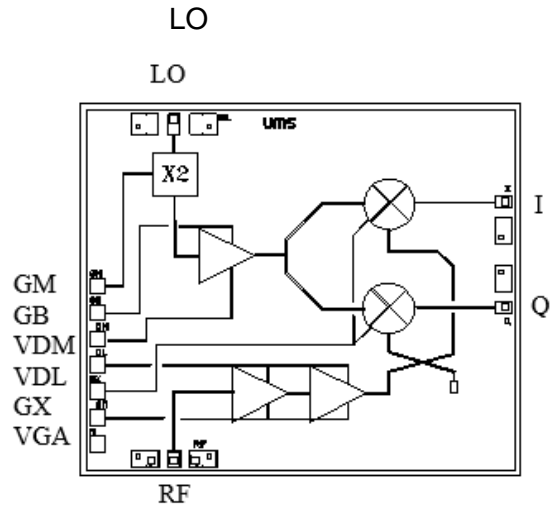
## 24-30GHz Integrated Down Converter

### GaAs Monolithic Microwave IC

#### Description

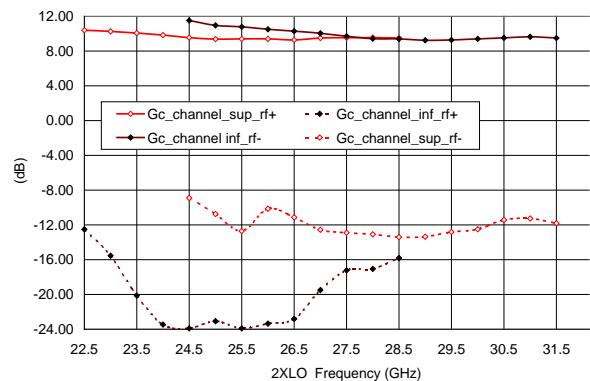
The CHR2295-99F is a multifunction chip which integrates a LO time two multiplier, a balanced cold FET mixer, and a RF LNA. It is designed for a wide range of applications, typically commercial communication systems. The backside of the chip is both RF and DC grounds. This helps simplify the assembly process.

The circuit is manufactured with a pHEMT process, 0.25µm gate length, via holes through the substrate, air bridges and electron beam gate lithography. It is available in chip form.



#### Main Features

- Broadband performances: 24-30GHz
- 11dB conversion gain
- 3.5dB noise figure, for IF>0.1GHz
- 10dBm LO input power
- -10dBm RF IP@1dB gain comp.
- Low DC power: 120mA@3.5V
- Chip size: 2.49x1.97x0.10mm



Conversion Gain & Image suppression  
@IF=1.5GHz (test board losses included)

#### Main Electrical Characteristics

Tamb. = 25°C

Symbol	Parameter	Min	Typ	Max	Unit
F <sub>RF</sub>	RF frequency range	24		30	GHz
F <sub>LO</sub>	LO frequency range	12		15	GHz
F <sub>IF</sub>	IF frequency range	DC		1.5	GHz
G <sub>c</sub>	Conversion gain	8.5	11		dB

### Electrical Characteristics for Broadband Operation

Tamb = +25°C, Vd = 3.5V

Symbol	Parameter	Min	Typ	Max	Unit
F <sub>RF</sub>	RF frequency range	24		30	GHz
F <sub>LO</sub>	LO frequency range	12		15	GHz
F <sub>IF</sub>	IF frequency range	DC		1.5	GHz
G <sub>c</sub>	Conversion gain <sup>(1)</sup>	8.5	11		dB
NF	Noise Figure, for IF>0.1GHz		3.5		dB
P <sub>LO</sub>	LO Input power		10		dBm
Img Sup	Image Suppression	15	17		dBc
P1dB	Input power at 1dB gain compression		-10		dBm
LO VSWR	Input LO VSWR <sup>(1)</sup>		2.0:1		
RF VSWR	Input RF VSWR <sup>(1)</sup>		3.0:1		
I <sub>d</sub>	Bias current <sup>(2)</sup>		120		mA

(1) On Wafer measurements

(2) Current source biasing network is recommended. Optimum performances will be achieved for I<sub>dm</sub>=50mA and I<sub>dl</sub>=70mA

### Absolute Maximum Ratings

Tamb. = 25°C <sup>(1)</sup>

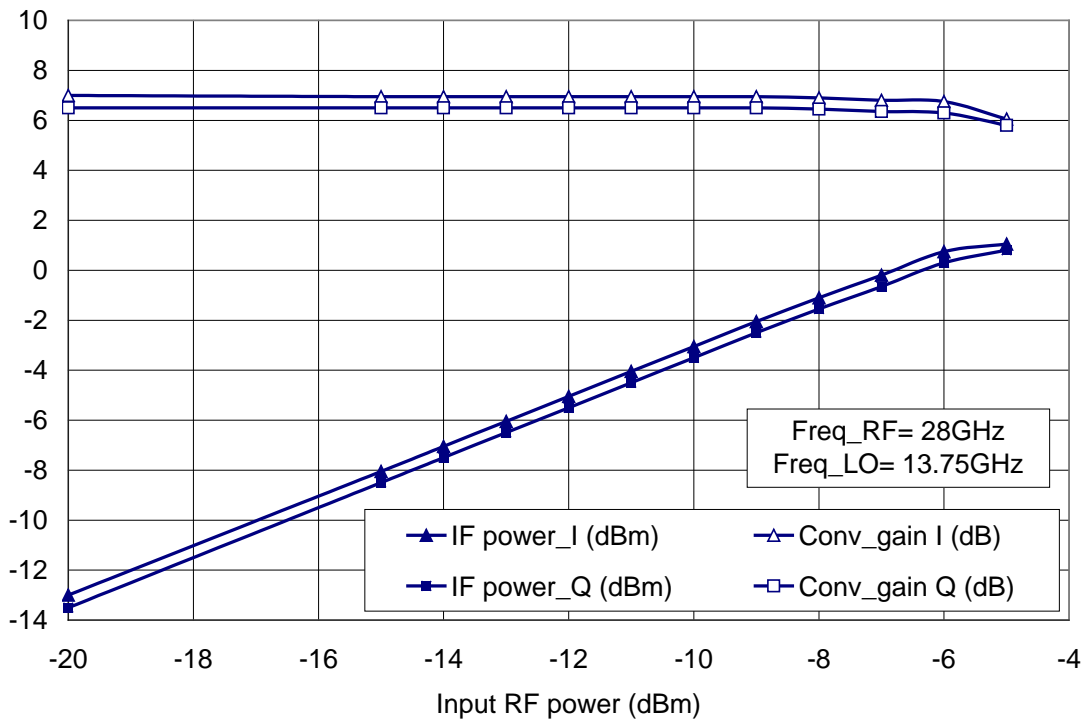
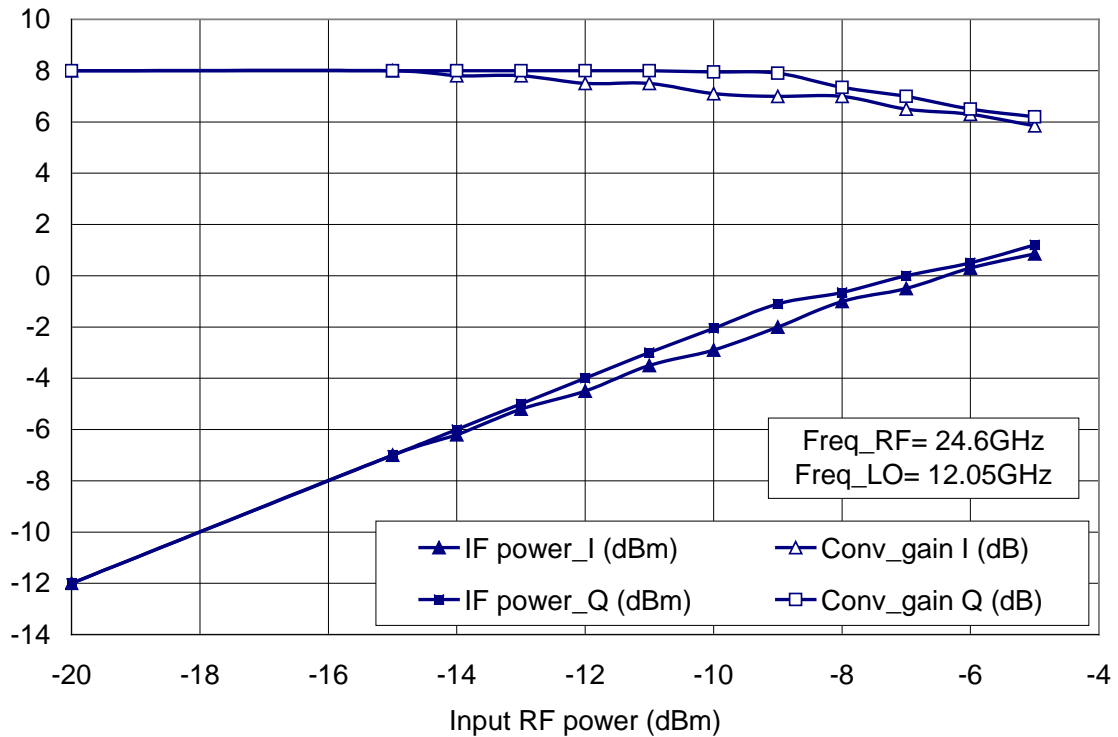
Symbol	Parameter	Values	Unit
V <sub>d</sub>	Drain bias voltage	4.0	V
I <sub>d</sub>	Drain bias current	200	mA
V <sub>g</sub>	Gate bias voltage	-2.0 to +0.4	V
P <sub>in</sub>	Maximum peak input power overdrive <sup>(2)</sup>	+15	dBm
T <sub>a</sub>	Operating temperature range	-40 to +85	°C
T <sub>stg</sub>	Storage temperature range	-55 to +150	°C

(1) Operation of this device above anyone of these parameters may cause permanent damage.

(2) Duration < 1s.

**Typical On-wafer Measurements**

Bias Conditions :  $V_{dm} = V_{dl} = 3.5V$ ,  $V_{gm} = -0.9V$ ,  $V_{gb} = -0.3V$ ,  $V_{gx} = -0.7V$ ,  $V_{ga} = -0.2V$



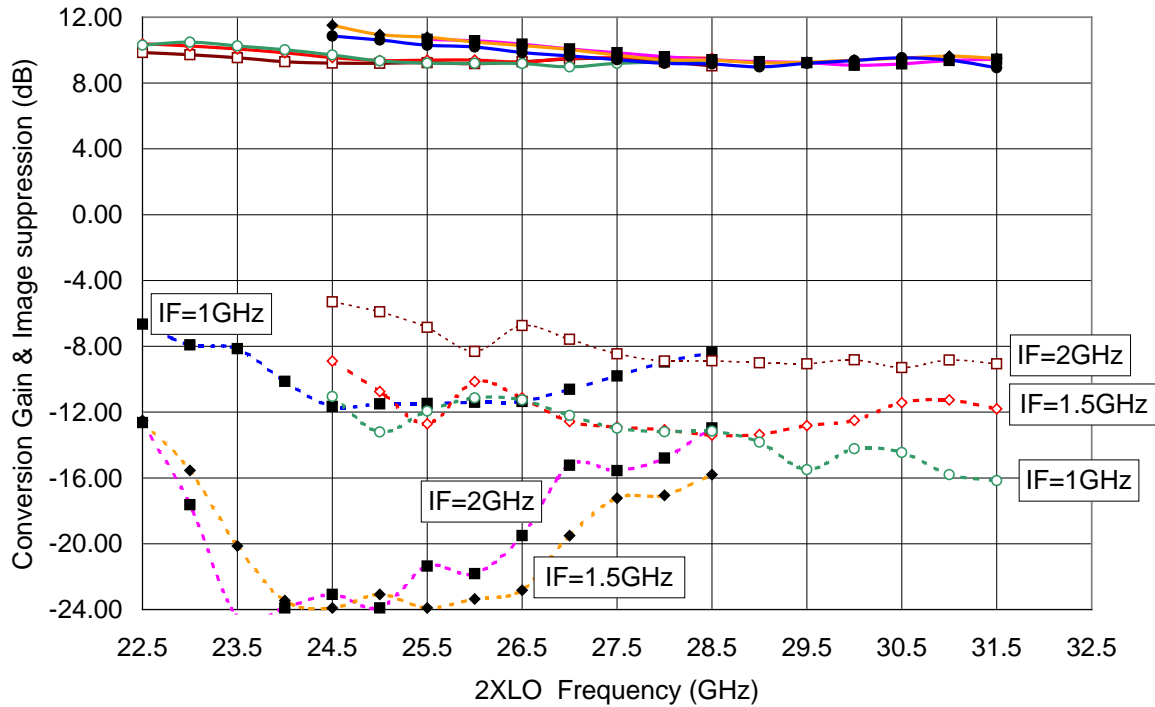
**Input RF compression by channel**



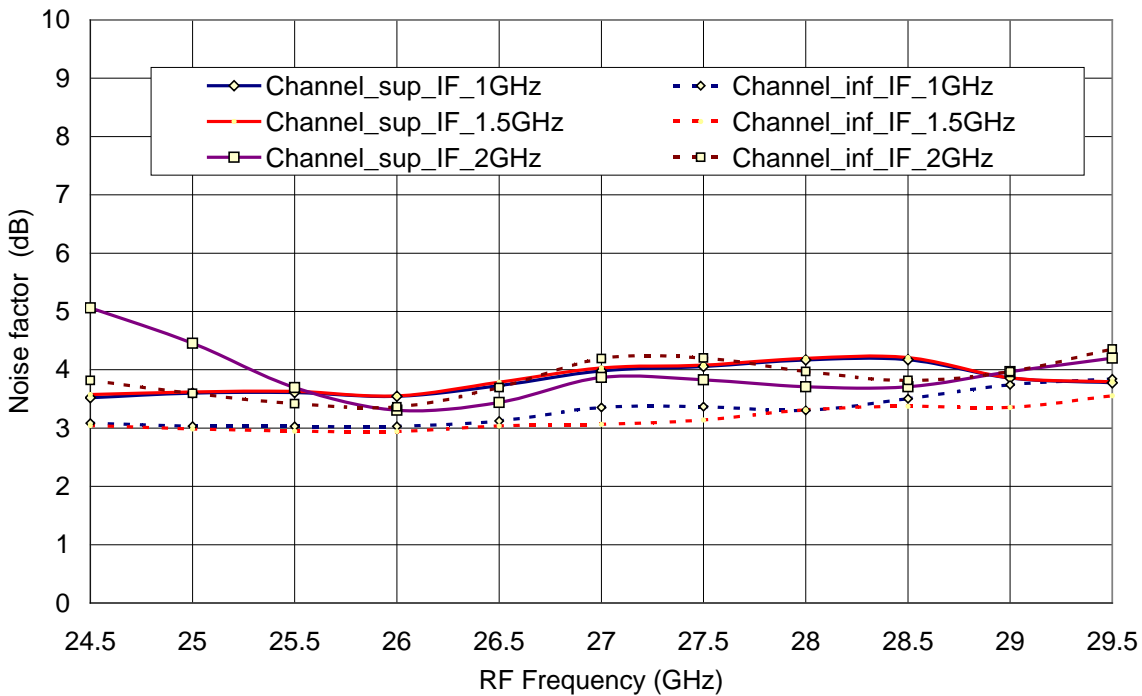
## Typical On-board Measurements

Bias Conditions :  $V_{dm} = V_{dl} = 3.5V$ ,  $V_{gm} = V_{gx} = -0.9V$ ,  $V_{gb} = V_{ga} = -0.3V$

All these measurements include the losses from the test board (typically 1dB for the conversion gain and 0.5dB for the Noise Figure).

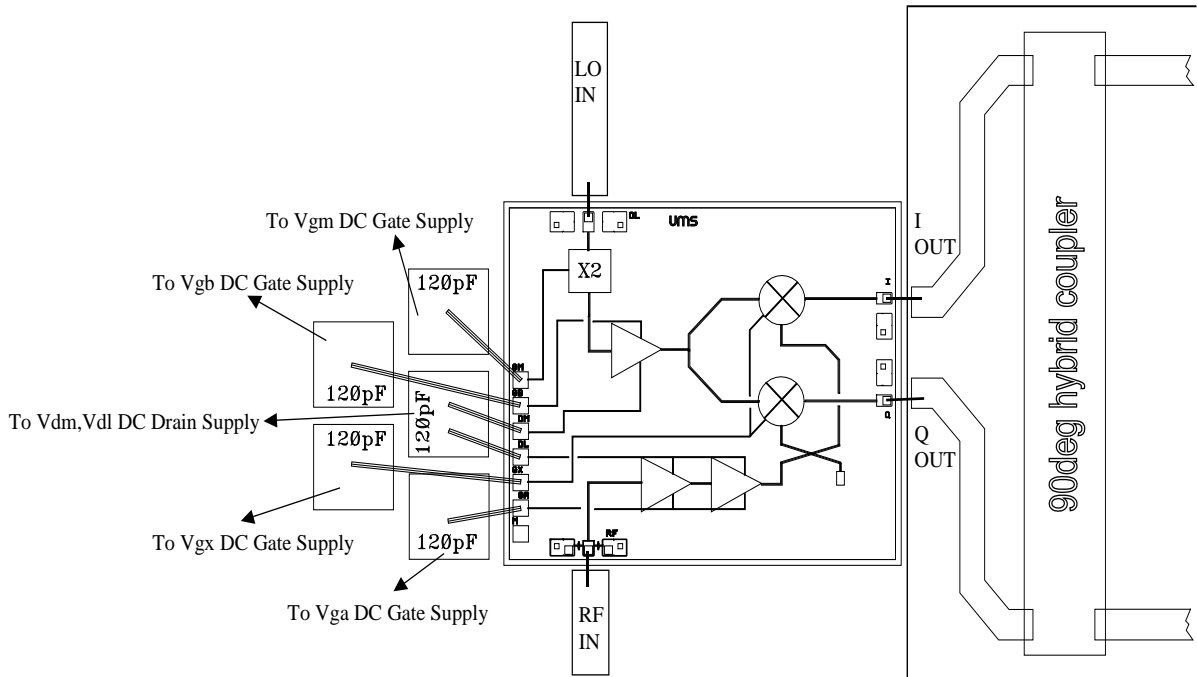


**Conversion gain & Image suppression versus IF frequency**

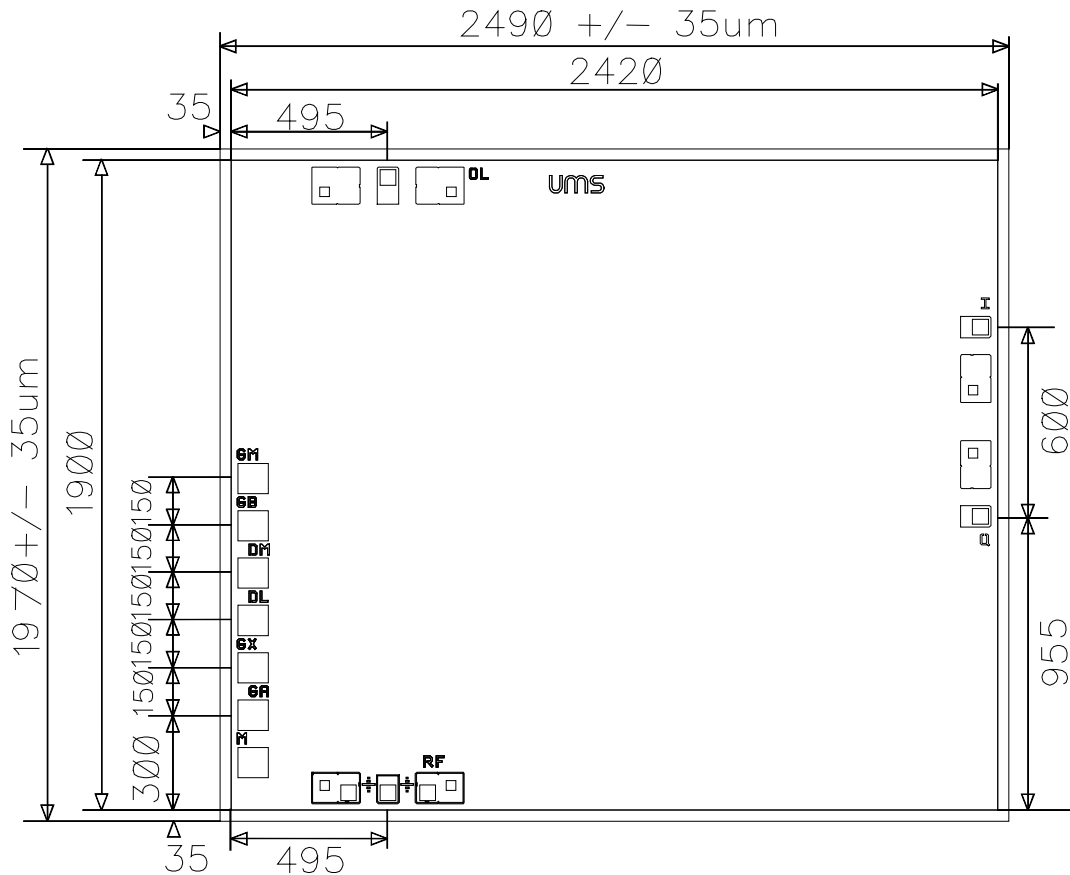


**Noise figure supradynic & infradyne versus IF frequency**

**Chip Assembly and Mechanical Data**



Note: Supply feed should be bypassed. 25µm diameter gold wire is recommended



**Bonding pad positions**  
(Chip thickness: 100µm. All dimensions are in micrometers)

### **Recommended ESD management**

Refer to the application note AN0020 available at <https://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS products.

### **Recommended environmental management**

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <https://www.ums-rf.com>.